

**Amendments to the Claims**

This listing of claims will replace all prior listings of claims in the application.

**Listing of Claims**

Claims 1-14 cancelled.

15. (New) A method of manufacturing a wireless suspension blank, said method comprising the steps of:

providing a three-layer laminate including a metallic layer having spring properties, a conductive layer laminated on the metallic layer through an electrically insulating layer, the insulating layer including a core-insulating layer and adhesive layers disposed on opposite sides of the core-insulating layer;

photo-etching the metallic layer and the conductive layer;

forming a resist pattern for the insulating layer; and  
wet etching the insulating layer through the resist pattern such that a ratio of higher etching rate to lower etching rate of the respective layers of the insulating layer is between 6:1 and 1:1.

16. (New) The method of Claim 15 wherein the ratio of higher etching rate to lower etching rate of the respective layers of the insulating layer is between 4:4 and 1:1.

17. (New) The method of Claim 15 wherein said step of providing includes providing a three-layer laminate wherein the adhesive strength of the adhesive layers relative to the metallic layer, the conductive layer and the core-insulating layer is at least 300 g/cm.

18. (New) The method of Claim 15 wherein said step of providing includes providing a three-layer laminate wherein the ratio of the thickness of the core-insulating layer to the thickness of the adhesive layers is a maximum of 4:1.

19. (New) The method of Claim 15 wherein said step of providing includes providing an insulating layer having at least one layer of polyimide resin.

20. (New) The method of Claim 15 wherein said step of providing includes providing an insulating layer constructed entirely of polyimide resin.

21. (New) The method of Claim 15 wherein said step of wet etching includes wet etching the insulating layer in alkali solution.

22. (New) The method of Claim 15 wherein said step of forming a resist pattern is performed after said step of photo-etching and includes forming respective resist patterns on the metallic layer and the conductive layer on sides thereof facing away from the insulating layer, and thereafter wet etching the insulating layer through the respective resist patterns.

23. (New) A method of manufacturing a wireless suspension blank, said method comprising the steps of:

providing a two-layer laminate including a metallic layer having spring properties, an insulating layer laminated on the metallic layer, the insulating layer including a core-insulating layer of polyimide resin and adhesive layers of polyimide resin laminated on the core-insulating layer;

photo-etching the metallic layer;

forming a wiring part on the insulating layer by the semi-additive method;

forming a resist pattern for the insulating layer; and  
wet etching the insulating layer through the resist pattern such that the ratio of higher etching rate to lower etching rate of the respective layers of the insulating layer is between 6:1 and 1:1.

24. (New) The method of Claim 23 wherein the ratio of higher etching rate to lower etching rate of the respective layers of the insulating layer is between 4:1 and 1:1.

25. (New) The method of Claim 23 wherein said step of providing includes providing a two-layer laminate wherein the adhesive strength of the adhesive layers is at least 300 g/cm.

26. (New) The method of Claim 23 wherein said step of providing includes providing a two-layer laminate wherein the ratio of the thickness of the core-insulating layer to the thickness of the adhesive layers is a maximum of 4:1.

27. (New) The method of Claim 23 wherein said step of wet etching includes wet etching the insulating layer with alkali solution.

28. (New) The method of Claim 23 wherein said step of forming a resist pattern is performed after said step of photo-etching and after said step of forming a wiring part, and said step of forming a resist pattern includes forming respective resist patterns on the wiring part and on the metallic layer, and thereafter wet etching the insulating layer through the respective resist patterns.